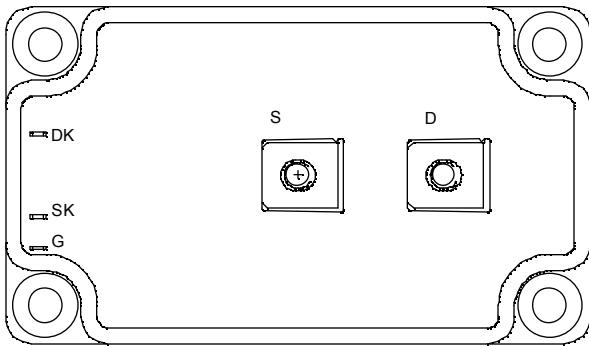
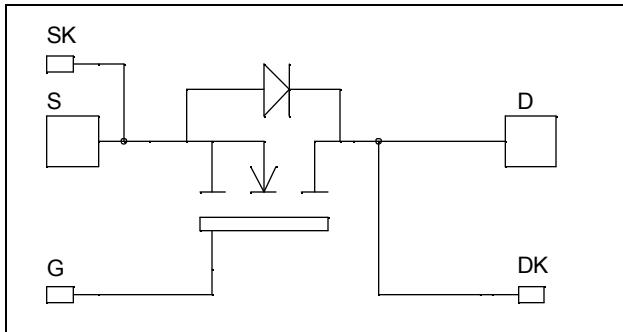


***Single Switch
MOSFET Power Module***

$V_{DSS} = 100V$
 $R_{DSon} = 2.25m\Omega$ typ @ $T_j = 25^\circ C$
 $I_D = 570A^*$ @ $T_c = 25^\circ C$



Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

Features

- Power MOS V® FREDFETs
 - Low R_{DSon}
 - Low input and Miller capacitance
 - Low gate charge
 - Avalanche energy rated
 - Fast intrinsic diode
 - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
 - Symmetrical design
 - M5 power connectors
- High level of integration
- AlN substrate for improved thermal performance

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Low profile

Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V_{DSS}	Drain - Source Breakdown Voltage	100	V
I_D	Continuous Drain Current	$T_c = 25^\circ C$	A
		$T_c = 80^\circ C$	
I_{DM}	Pulsed Drain current	1900	
V_{GS}	Gate - Source Voltage	± 30	V
R_{DSon}	Drain - Source ON Resistance	2.5	$m\Omega$
P_D	Maximum Power Dissipation	$T_c = 25^\circ C$	W
I_{AR}	Avalanche current (repetitive and non repetitive)	100	A
E_{AR}	Repetitive Avalanche Energy	50	mJ
E_{AS}	Single Pulse Avalanche Energy	3000	

* Specification of MOSFET device but output current must be limited to 500A to not exceed a delta of temperature greater than 100°C for the connectors.

 **CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handing Procedures Should Be Followed.

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0\text{V}$, $V_{DS} = 100\text{V}$	$T_j = 25^\circ\text{C}$			400	μA
		$V_{GS} = 0\text{V}$, $V_{DS} = 80\text{V}$	$T_j = 125^\circ\text{C}$			2000	
$R_{DS(on)}$	Drain – Source on Resistance	$V_{GS} = 10\text{V}$, $I_D = 200\text{A}$			2.25	2.5	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 10\text{mA}$		2		4	V
I_{GSS}	Gate – Source Leakage Current	$V_{GS} = \pm 30\text{ V}$, $V_{DS} = 0\text{V}$				± 400	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}$ $V_{DS} = 25\text{V}$ $f = 1\text{MHz}$		40			nF
C_{oss}	Output Capacitance			15.7			
C_{rss}	Reverse Transfer Capacitance			5.9			
Q_g	Total gate Charge	$V_{GS} = 10\text{V}$ $V_{Bus} = 50\text{V}$ $I_D = 400\text{A}$		1360			nC
Q_{gs}	Gate – Source Charge			240			
Q_{gd}	Gate – Drain Charge			720			
$T_{d(on)}$	Turn-on Delay Time	Inductive switching $V_{GS} = 15\text{V}$ $V_{Bus} = 66\text{V}$ $I_D = 400\text{A}$		160			ns
T_r	Rise Time			240			
$T_{d(off)}$	Turn-off Delay Time			500			
T_f	Fall Time		$R_G = 1.25\Omega$	160			
E_{on}	Turn-on Switching Energy ①	Inductive switching @ 25°C $V_{GS} = 15\text{V}$, $V_{Bus} = 66\text{V}$ $I_D = 400\text{A}$, $R_G = 1.25\Omega$		2.2			mJ
E_{off}	Turn-off Switching Energy ②			2.41			
E_{on}	Turn-on Switching Energy ①	Inductive switching @ 125°C $V_{GS} = 15\text{V}$, $V_{Bus} = 66\text{V}$ $I_D = 400\text{A}$, $R_G = 1.25\Omega$		2.43			mJ
E_{off}	Turn-off Switching Energy ②			2.56			

Source - Drain diode ratings and characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I_S	Continuous Source current (Body diode)		$T_c = 25^\circ\text{C}$			570*	A
			$T_c = 80^\circ\text{C}$			429	
V_{SD}	Diode Forward Voltage	$V_{GS} = 0\text{V}$, $I_S = -400\text{A}$				1.3	V
dv/dt	Peak Diode Recovery ③					5	V/ns
t_{rr}	Reverse Recovery Time	$I_S = -400\text{A}$ $V_R = 66\text{V}$ $di/dt = 400\text{A}/\mu\text{s}$	$T_j = 25^\circ\text{C}$			190	ns
			$T_j = 125^\circ\text{C}$			370	
Q_{rr}	Reverse Recovery Charge	$I_S = -400\text{A}$ $V_R = 66\text{V}$ $di/dt = 400\text{A}/\mu\text{s}$	$T_j = 25^\circ\text{C}$		1.6		μC
			$T_j = 125^\circ\text{C}$		6.8		

① E_{on} includes diode reverse recovery.

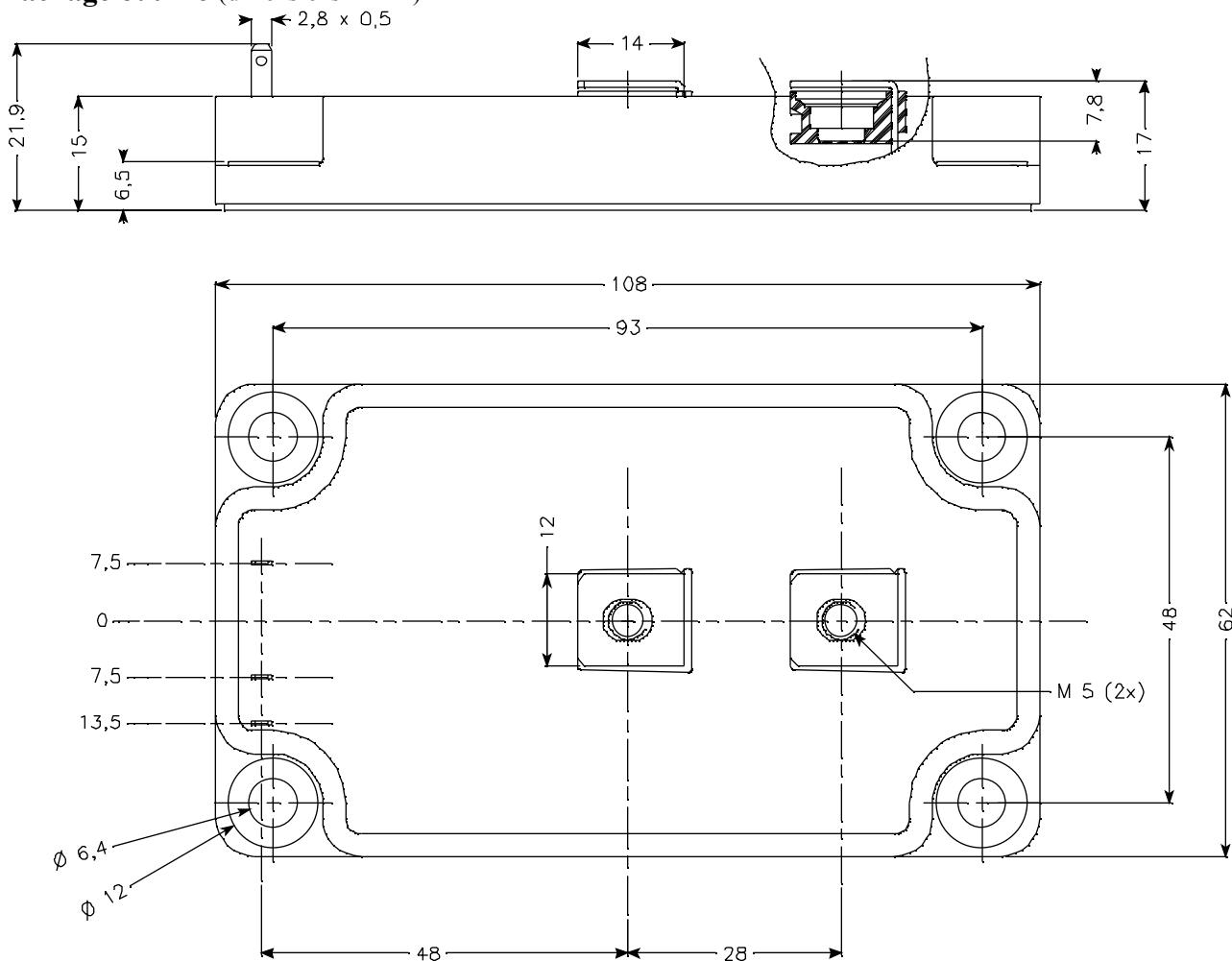
② In accordance with JEDEC standard JESD24-1.

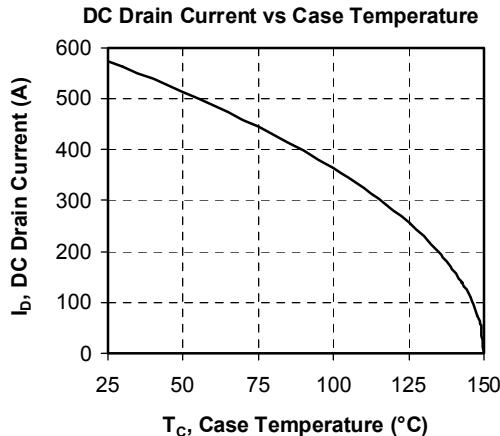
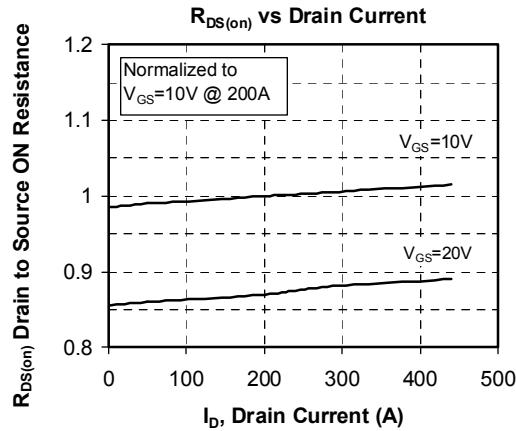
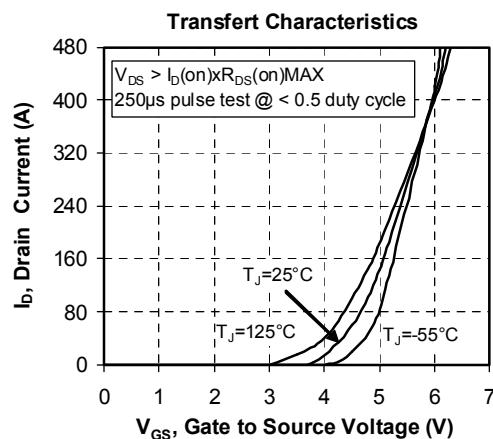
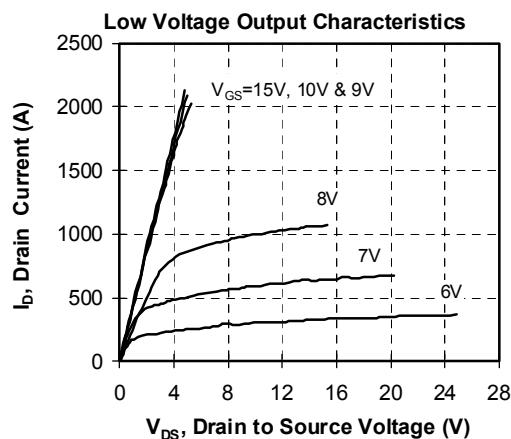
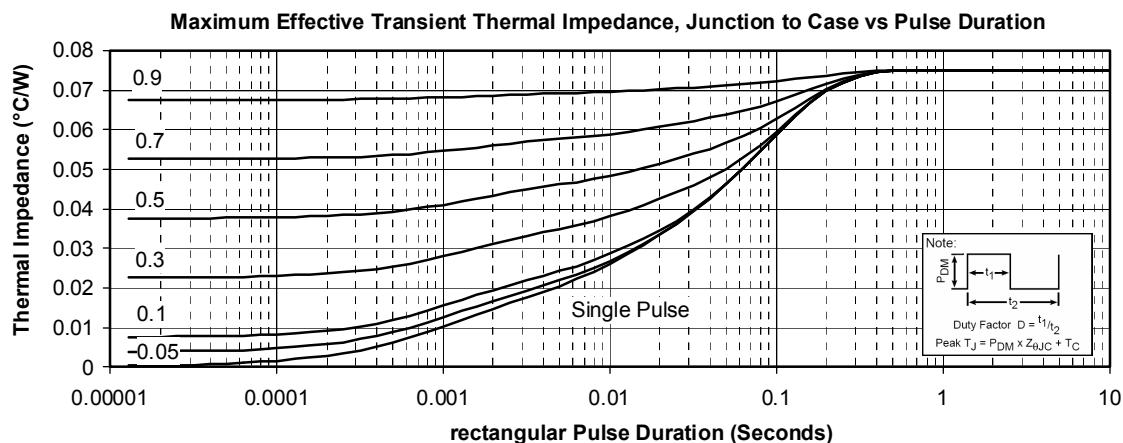
③ dv/dt numbers reflect the limitations of the circuit rather than the device itself.

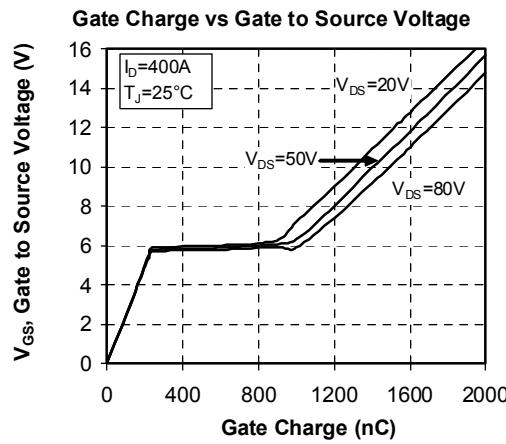
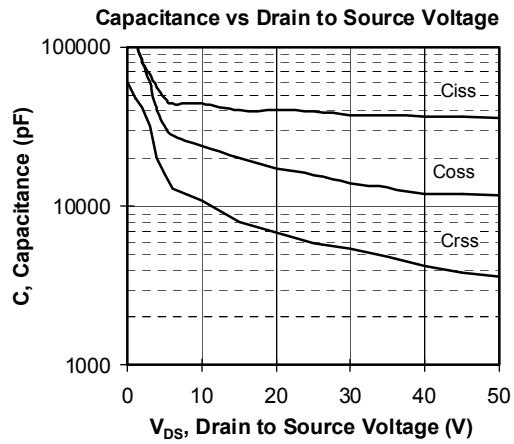
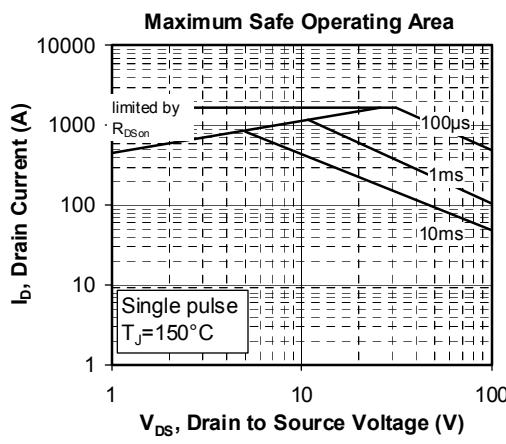
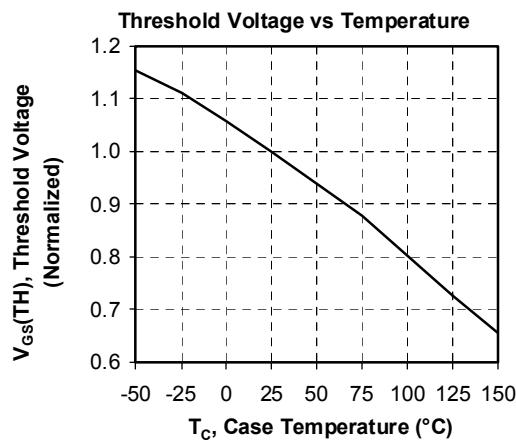
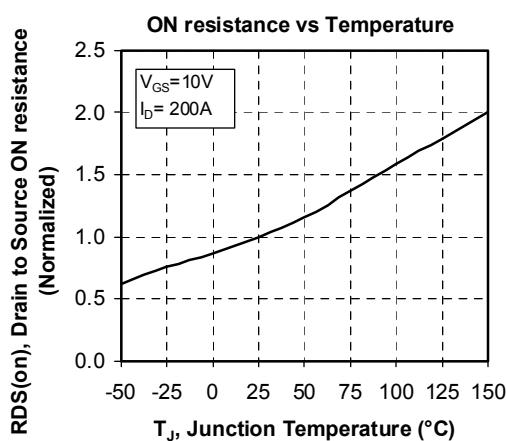
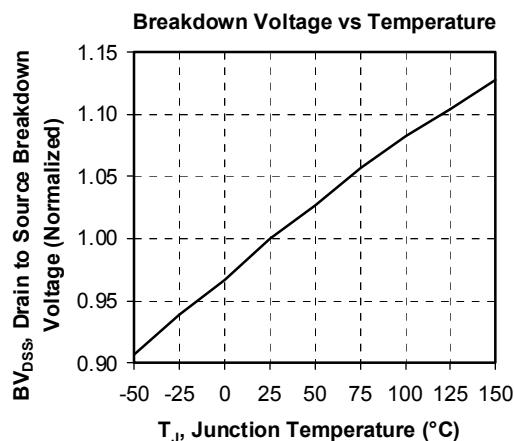
$I_S \leq -570\text{A}$ $di/dt \leq 400\text{A}/\mu\text{s}$ $V_R \leq V_{DSS}$ $T_j \leq 150^\circ\text{C}$

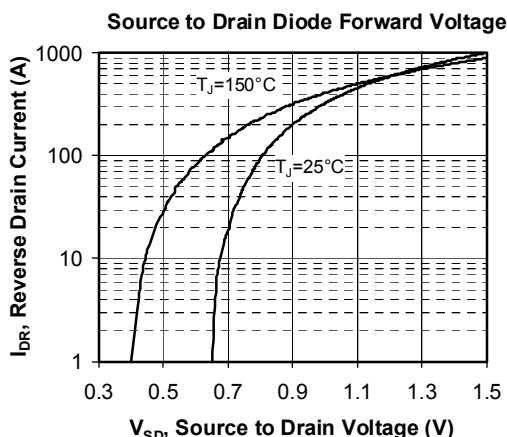
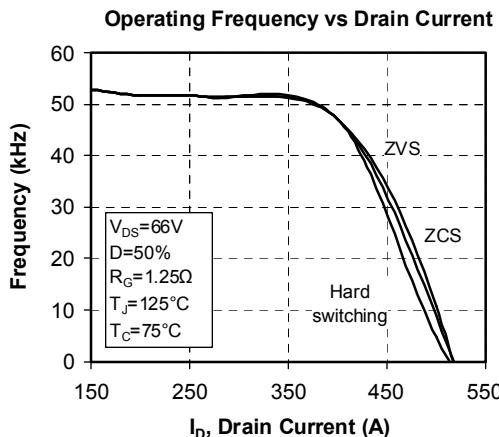
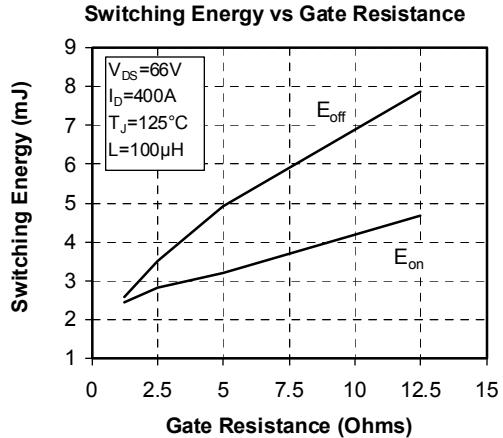
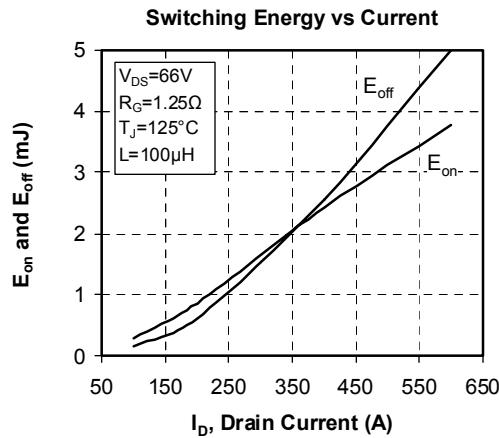
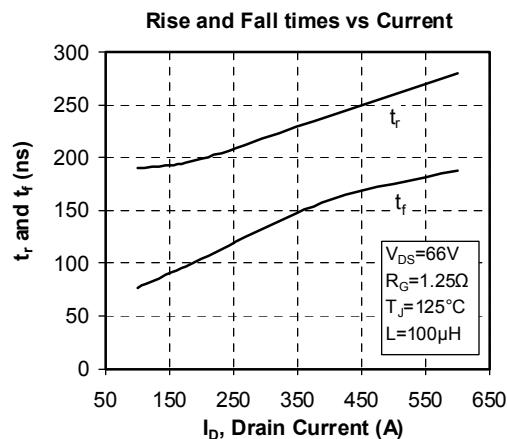
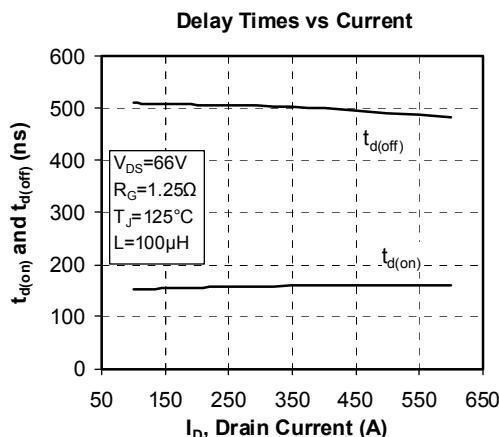
Thermal and package characteristics
Symbol Characteristic

			<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
R_{thJC}	Junction to Case				0.075	°C/W
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, I Isol<1mA, 50/60Hz		2500			V
T_J	Operating junction temperature range		-40		150	
T_{STG}	Storage Temperature Range		-40		125	°C
T_C	Operating Case Temperature		-40		100	
Torque	Mounting torque	To heatsink For terminals	M6 M5	3 2	5 3.5	N.m
Wt	Package Weight				280	g

Package outline (dimensions in mm)


Typical Performance Curve






APT reserves the right to change, without notice, the specifications and information contained herein

APT's products are covered by one or more of U.S patents 4,895,810 5,045,903 5,089,434 5,182,234 5,019,522 5,262,336 6,503,786 5,256,583 4,748,103 5,283,202 5,231,474 5,434,095 5,528,058 and foreign patents. U.S and Foreign patents pending. All Rights Reserved.